

Part Number: **MMBZ52xxBW-(p)-F (Date Code 0627+)**
Weight (mg): 6.0068

p = package designator
See Data Sheet

x= 21, 23, 25, 26, 27, 28, 29, 30, 31, 32, 34, 35, 36, 37, 39,
40, 41, 42, 43, 45, 46, 48, 50, 51, 52, 54, 55, 56, 57, 58, 59

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	100.00%	0.98	0.0588	1000000	9789
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	27.74	1.666	576500	159894
		Ni	7440-02-0	41.00%			410000	113714
		Mn	7439-96-5	0.60%			6000	1664
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	277
		Co	7440-48-4	0.50%			5000	1387
		Si	7440-21-3	0.15%			1500	416
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.05	0.0629	1000000	10471
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.21	0.0125	1000000	2081
Encapsulation	KTMC-1050G	SiO2	60676-86-0	69.00%	68.97	4.1427	690000	475871
		Epoxy Resin	29690-82-2	14.00%			140000	96554
		Phenol Resin	9003-35-4	7.00%			70000	48277
		Mg(OH)2	1309-42-8	8.00%			80000	55173
		C	1333-86-4	0.20%			2000	1379
		others	----	1.80%			18000	12414
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.06	0.0639	1000000	10638
Total					100.00	6.0068		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)